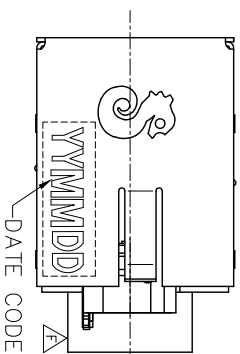
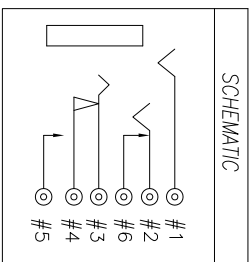
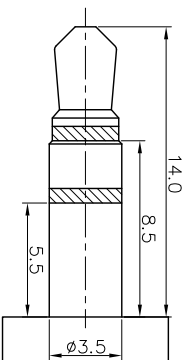


RECOMMEND PCB LAYOUT (TOP VIEW)
(TOLERANCE: ±0.05)



- SPECIFICATIONS:
- INSULATION RESISTANCE BETWEEN ANY ADJACENT OPEN CIRCUIT TERMINAL SHELL NOT BE LESS THAN 100MΩ. MEASURED BY 500 VDC MEGGER.
 - CONTACT RESISTANCE: 30mΩ. MAX. (200mΩ MAX: METAL TO EARTH TO SHIELDING)
 - INSULATION VOLTAGE WITHSTAND: 500V AC FOR ONE MINUTE.
 - UNLESS OTHERWISE SPECIFIED. TEST IS TO BE MADE AT 5-35°C IN TEMPERATURE AND 45-85% IN HUMIDITY. BUT, IF ANY VAGUE DATA IS OCCURED ON TEST RESULT, ANOTHER TEST SHALL BE MADE AT 20°C±2°C IN TEMP., 60-70% IN HUMIDITY.
 - LIFE TEST: 5,000 CYCLES MIN. (NON-LOAD)
 - INSERTION FORCE: 0.4 - 3Kg.
 - WITHDRAWAL FORCE: 0.3 - 2Kg.
 - AFTER LIFE TEST, CONTACT RESISTANCE: 50mΩ MAX.
 - AFTER HUMIDITY TEST, INSULATION RESISTANCE: 50MΩ MIN.
 - MARKING: MARK "S" ON TOP OF CONNECTOR.
 - PACKAGING: TAPE & REEL.
 - TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC
 - GREEN PRODUCT IDENTIFICATION MARK ON JACK:
 - GREEN PRODUCT IDENTIFICATION LABEL ON PACKAGING: **G.P. PASS**
 - FOR LEAD-FREE PROCESS.

REV.	ECN NO.	OR DESCRIPTION	REVISED	DATE
C	ECN NO. S110320		Cerry	2011.03.28
D	ECN NO. C130115	UPDATE DRAWING	ZJK	2013.06.04
E	ECN NO. C130206	MODIFY BODY	ZLS	2014.4.1
F	ECN NO. C140237	UPDATE DRAWING	ZLS	2014.11.07

H	SHIELDING	1	PHOSPHOR BRONZE 0.2t	Ni 60u" MIN.
G	TRANSFER TERMINAL	1	PHOSPHOR BRONZE 0.2t	GOLD FLASH ON CONTACT AREA.
F	BREAK TERMINAL	1	PHOSPHOR BRONZE 0.2t	Sn 120u" ON SOLDER; ALL OVER Ni 50u" .
E	RING SPRING	1	PHOSPHOR BRONZE 0.2t	
D	SHUNT TERMINAL-A	1	BRASS 0.25t	
C	TIP SPRING	1	PHOSPHOR BRONZE 0.25t	Ag 20u" MIN OVER Ni 60u" MIN.
B	EARTH	1	COPPER ALLOY 0.2t	
A	BODY	1	HIGH TEMP THERMOPLASTIC UL 94V-0	PINK (701C)
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
UNLESS OTHERWISE SPECIFIED TOLERANCES				
Singatron Enterprise Co., Ltd. 信登企業股份有限公司				
TITLE		3.5Ø PHONE JACK		
DWN	ZLS	14/11/18	PART NO. 2SI-S351-008	
CHKD	BULLY	14/11/18	SCALE: 4:1	UNIT: mm
APVD	Z22	14/11/18	SIZE: A3	SHEET: 1 OF 1 REV: F
CUSTOMER COPY				